

I/O module with CAN FD

At the fair, Microcontrol (Germany) shows its generation of I/O modules, which are CAN FD-capable.

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Microcontrol is part of the Embedded World 2018 in Nuremberg, Germany in hall B1, stand 440 (Photo: Microcontrol)

Microcontrol's I/O modules are suitable for harsh environments. Featuring operating temperature between -40 °C to +85 °C, IP66, and a resolution of up to 24 bit these components fit into heavy-duty applications.

In the future, the I/O modules will be based on a consistent hardware platform. An ARM-based controller will provide a 50-% processing power increase. The considerably reduced power consumption of the CPU results in less heat emission. According to the company, this will reduce costs for control cabinet equipment - or even make them redundant. A consistent hardware platform will make cross-product developments and validations (e.g. EMC and environmental tests) more efficient, safer, and easier to realize, the company added.

The embedded controller architecture is made for the future and provides the opportunity to migrate to CAN FD at any time. The I/O modules will also be based on a consistent, cross-product software platform. Some examples: individual customer specifications and adaptations can be realized on all Microcontrol modules. Improved system tests facilitate error detection and increase availability.

The modules will be equipped with dynamic PDO mapping, a buffered real time clock and a standard CANopen Bootloader. The updated generation of I/O modules will be introduced step by step. First versions of the module generation are already available. They are also exhibited at the Embedded World 2018.

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